

# P-Channel 40-V (D-S) MOSFET

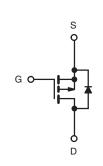
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω <b>)</b>	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
- 40	0.054 at V <sub>GS</sub> = - 10 V	- 4.5	9		
	0.072 at $V_{GS}$ = - 4.5 V	- 3.9	9		

#### **FEATURES**

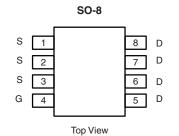
- Halogen-free According to IEC 61249-2-21
  Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

#### **APPLICATIONS**

CCFL Inverter



P-Channel MOSFET



Ordering Information: Si4447DY-T1-E3 (Lead (Pb)-free)							
Si4447DY-T1-GE3 (Lead (Pb)-free and Halogen-free)							

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \degree C$ , unless otherwise noted						
Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 40		V	
Gate-Source Voltage		V <sub>GS</sub>	± 16			
Continuous Drain Current $(T_J = 150 \ ^{\circ}C)^a$	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	- 4.5	- 3.3		
	T <sub>A</sub> = 70 °C		- 3.6	- 2.7		
Pulsed Drain Current		I <sub>DM</sub>	- 30		А	
Continuous Source Current (Diode Conduction) <sup>a</sup>		۱ <sub>S</sub>	- 1.7	- 0.9		
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	16			
Single Pulse Avalanche Energy		E <sub>AS</sub>	13		mJ	
	T <sub>A</sub> = 25 °C	- P <sub>D</sub>	2	1.1	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C		1.3	0.7		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55	to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	R <sub>thJA</sub>	50	62.5			
Maximum Junction-to-Ambient	Steady State		85	110	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	30	40			

Notes:

a. Surface mounted on 1" x 1" FR4 board.



FREE Available



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	•					•
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	- 0.8		- 2.2	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μA		- 40		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η = - 230 μΑ		3.4		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 16 V$			± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55 \text{ °C}$			- 1 - 10	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 V, V_{GS} = -10 V$	- 20			Α
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -4.5 \text{ A}$ $V_{GS} = -15 \text{ V}, \text{ I}_{D} = -4.5 \text{ A}$		0.045 0.059	0.054 0.072	Ω
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 4.5 A		13		S
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = - 1.7 A, V <sub>GS</sub> = 0 V		- 0.79	- 1.2	V
Dynamic <sup>b</sup>	•					
Input Capacitance	C <sub>iss</sub>			805		pF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz		120		
Reverse Transfer Capacitance	C <sub>rss</sub>			85		
Total Gate Charge	Qg			9	14	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -20$ V, $V_{GS} = -4.5$ V, $I_{D} = -4.5$ A		2		nC
Gate-Drain Charge	Q <sub>gd</sub>			3.6		
Gate Resistance	R <sub>g</sub>	f = 1 MHz		11.5	18	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			8	13	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 15 $\Omega$		12	18	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_{D}\cong$ - 1 A, $V_{GEN}$ = - 10 V, $R_{g}$ = 6 $\Omega$		74	110	ns
Fall Time	t <sub>f</sub>			38	60	]
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 1.7 A, dl/dt = 100 A/μs		27	45	]
Body Diode Reverse Recovery Charge	$Q_{rr}$ $I_F = 1.7 A, di/dt = 100 A/\mu s$			17	26	nC

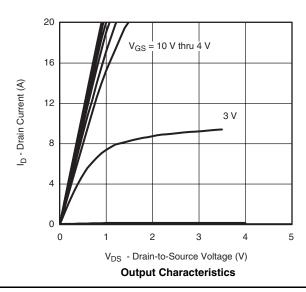
Notes:

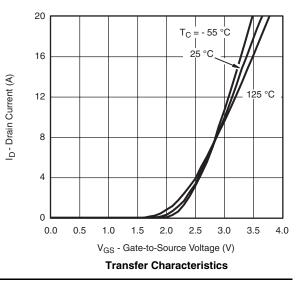
a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

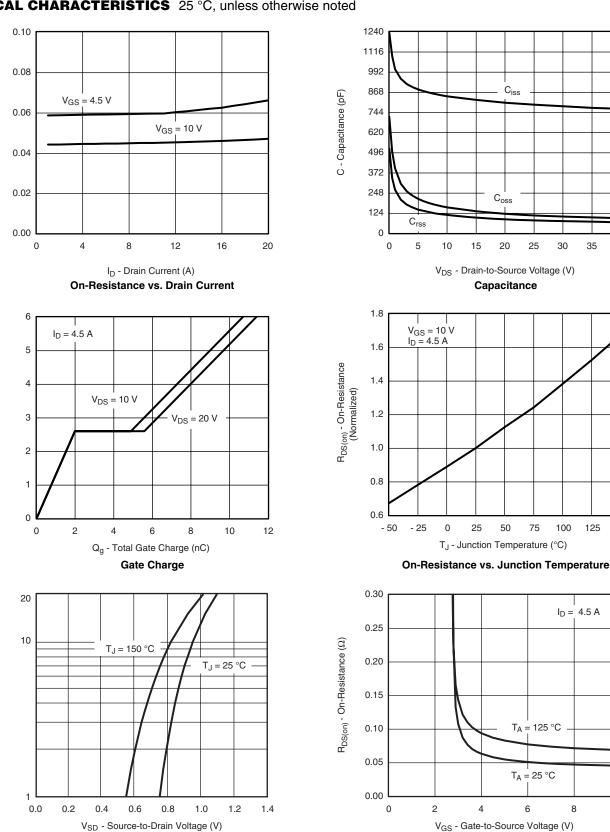
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







**Si4447DY** 

40

150

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

VISHAY

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - On-Resistance ( $\Omega)$ 

V<sub>GS</sub> - Gate-to-Source Voltage (V)

Is - Source Current (A)

Document Number: 73662 S09-0322-Rev. B, 02-Mar-09

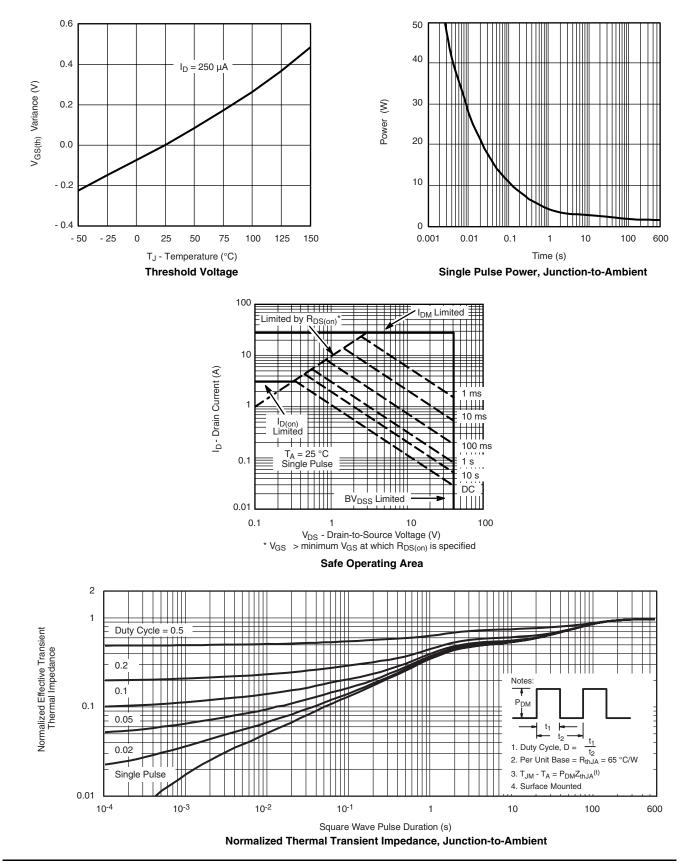
Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

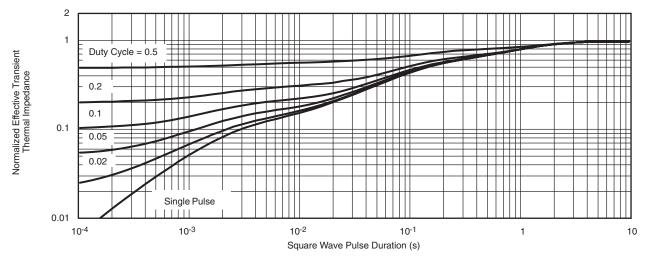




Si4447DY

## Vishay Siliconix

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <u>www.vishay.com/ppg773662</u>.



# Package Information

Vishay Siliconix

# SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES			
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						

# **Application Note 826**

Vishay Siliconix



**RECOMMENDED MINIMUM PADS FOR SO-8** 



Recommended Minimum Pads Dimensions in Inches/(mm)

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